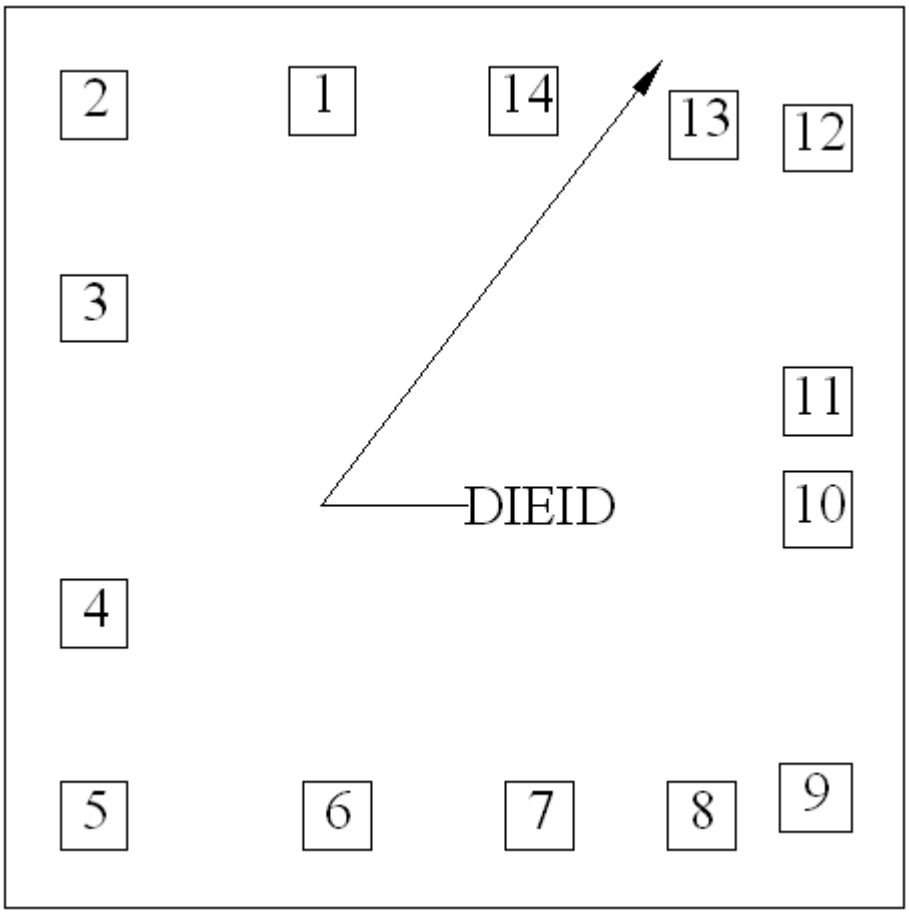
LP339 MDA MWA
ULTRA-LOW POWER QUAD COMPARATOR

August 12,2003

DIE LAYOUT (B-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LP339B	Bond Pad Opening Size (min)	90µm x 90µm
Die Step	B	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	1194µm x 1194µm 47.0mils x 47.0mils	Back Side Connection	Floating
Thickness	330µm Nominal		
Min Pitch	143µm Nominal		

Special Assembly Requirements:
Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (B -Step)

(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES X	Y	PAD SIZE X		Y
INPUT 1+	1	-175	474	90	x	90
INPUT 2-	2	-478	469	90	x	90
INPUT 2+	3	-478	198	90	x	90
INPUT 3-	4	-478	-208	90	x	90
INPUT 3+	5	-478	-476	90	x	90
INPUT 4-	6	-155	-476	90	x	90
INPUT 4+	7	113	-476	90	x	90
GND	8	328	-476	90	x	90
OUTPUT 4	9	480	-452	95	x	90
OUTPUT 3	10	482	-69	90	x	100
OUTPUT 2	11	482	74	90	x	90
OUTPUT 1	12	482	425	90	x	88
V+	13	331	442	90	x	90
INPUT 1-	14	93	474	90	x	90

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